

April 21, 2023

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SHINKO ELECTRIC INDUSTRIES CO., LTD.

Stock exchange code: 6967, TSE Prime

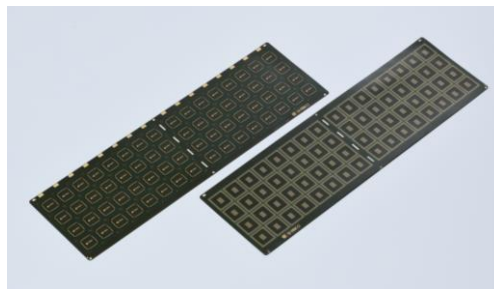
SHINKO ELECTRIC INDUSTRIES CO., LTD. Acquires IATF 16949 Certification for Plastic BGA Substrates

NAGANO, Japan, April 21, 2023 – SHINKO ELECTRIC INDUSTRIES CO., LTD. (SHINKO) announced acquiring IATF 16949 certification, an international quality management system standard for the automotive industry, for the design and manufacture of plastic BGA substrates for semiconductor memory.

Automotive semiconductors are in high demand as key components in car electronics, and SHINKO's plastic BGA substrates are used as highly dependable semiconductor package substrates for automobiles. As the speed and capacity of semiconductor memory for automobiles continues to grow, it is essential to provide products with high reliability and to further improve their quality. To meet the quality requirements of our customers, SHINKO has promoted the implementation of a quality management system based on IATF 16949 and, as a result of efforts to acquire this standard, has been certified.

IATF 16949 is an international standard for automotive industry-specific quality management systems, based on ISO 9001, with stringent requirements unique to the automotive industry. This standard has been adopted as the global procurement standard for automotive components by many automobile manufacturers and suppliers to the automotive industry worldwide.

Through this certification, SHINKO is committed to continuous quality improvement and a stable supply of high-quality products for automobiles.



Plastic BGA Substarates

Certification details

- 1) Registration standard
IATF16949-First Edition
- 2) Certification authority
Bureau Veritas Certification Holding
- 3) IATF Certification number
0466474
- 4) Certification authority certificate number
JP023232-IATF
- 5) Original approval date
January 13, 2023

6) Certified organization

SHINKO ELECTRIC INDUSTRIES CO., LTD. Plastic Laminated Package Div. II Arai Plant.

7) Scope of certification

Design and manufacturing of Substrate for semiconductor memory device.

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